MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS
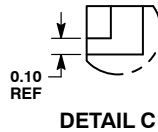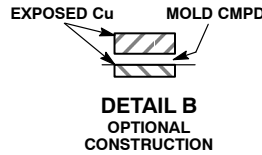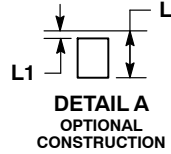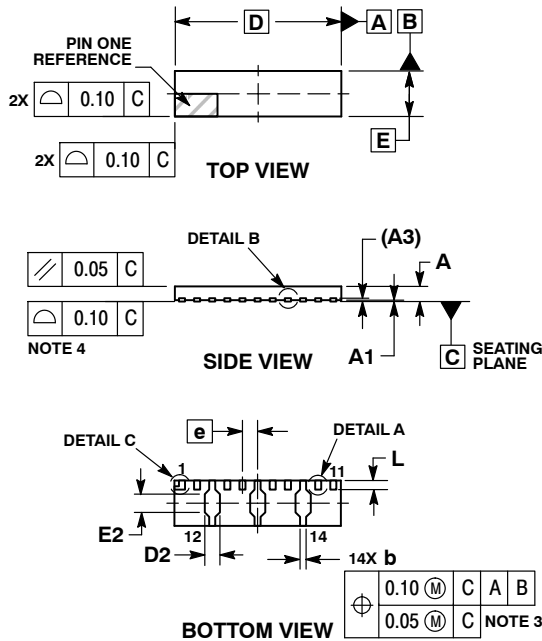
ON Semiconductor®

UDFN14, 5.5x1.5, 0.5P
CASE 517CN
ISSUE O

DATE 30 OCT 2012

SCALE 2:1

14

1

TOP VIEW

PIN ONE REFERENCE

2X ⌒ 0.10 C

2X ⌒ 0.10 C

D

A B

E

SIDE VIEW

0.05 C

0.10 C

NOTE 4

DETAIL B

(A3)

A

A1

C SEATING PLANE

BOTTOM VIEW

DETAIL C

e

DETAIL A

1

11

L

E2

12

14

D2

14X b

⊕ 0.10 Ⓜ C A B

0.05 Ⓜ C NOTE 3

DETAIL A
OPTIONAL CONSTRUCTION

L

L1

DETAIL B
OPTIONAL CONSTRUCTION

EXPOSED Cu   MOLD CMPD
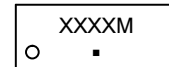
DETAIL C

0.10 REF

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

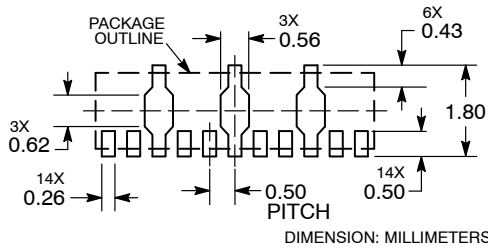| DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	5.50 BSC	
D2	0.45	0.55
E	1.50 BSC	
E2	0.50	0.70
e	0.50 BSC	
L	0.20	0.40
L1	0.00	0.05

GENERIC MARKING DIAGRAM*

XXXXM

○   ▪

XXXX = Specific Device Code
M = Date Code
▪ = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

RECOMMENDED SOLDERING FOOTPRINT*

PACKAGE OUTLINE

3X 0.56

6X 0.43

1.80

3X 0.62

14X 0.26

0.50 PITCH

14X 0.50

DIMENSION: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.